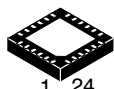


MECHANICAL CASE OUTLINE

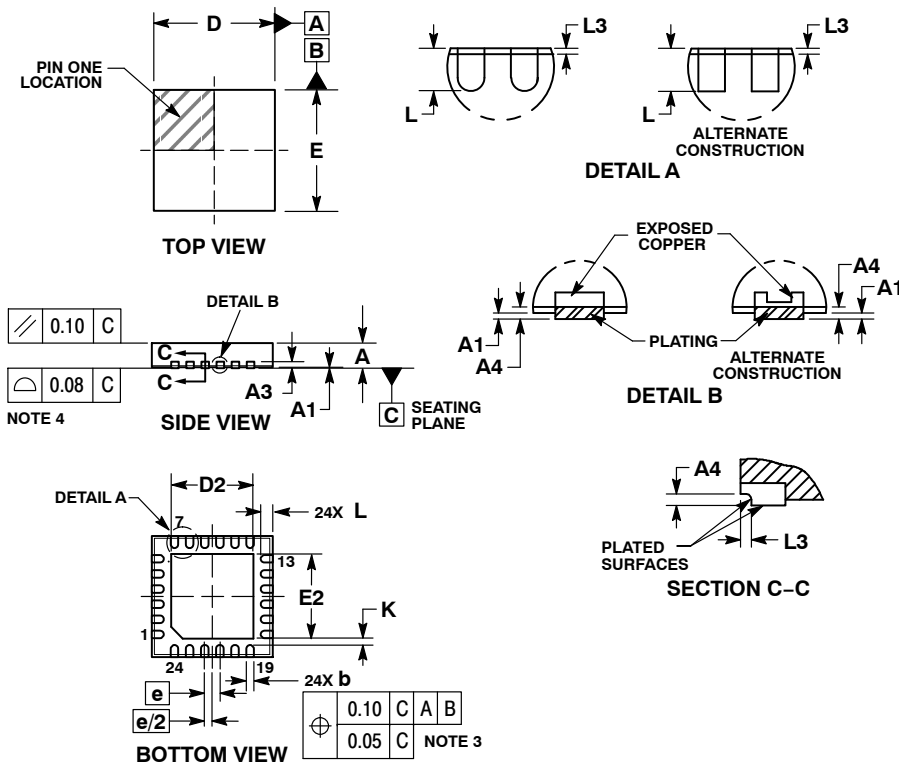
PACKAGE DIMENSIONS



SCALE 2:1

QFNW24 4x4, 0.5P
CASE 484AE
ISSUE A

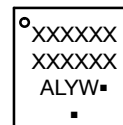
DATE 07 AUG 2018



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.
 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.80	0.85	0.90
A1	---	---	0.05
A3	0.20 REF		
A4	0.10	---	---
b	0.20	0.25	0.30
D	3.90	4.00	4.10
D2	2.70	2.80	2.90
E	3.90	4.00	4.10
E2	2.70	2.80	2.90
e	0.50 BSC		
K	0.20	---	---
L	0.35	0.40	0.45
L3	0.00	0.05	0.10

GENERIC MARKING DIAGRAM*

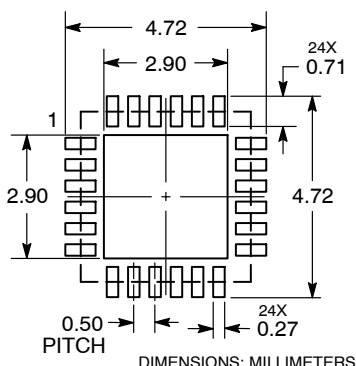


- XXXXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

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DESCRIPTION:	QFNW24 4x4, 0.5P	PAGE 1 OF 1

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